

IN THE CLAIMS

The claims are amended as follows:

1. (currently amended) An electronic component assembly, comprising:
a flexible printed circuit;
a first component electronically coupled with the flexible printed circuit;
a second component electronically coupled with the flexible printed circuit, the flexible printed circuit folded to position the components in generally mutually facing relation; ~~and~~[,]
an inter-component thermal management device disposed between the components, in thermal relation with the components, for removing or stabilizing thermal energy from the components during operation[.]; and
at least one second thermal management device thermally connected to the inter-component thermal management device.
2. (original) The electronic component assembly of claim 1, wherein at least one of the components is an electronic device, a memory device, a logic device or a microprocessor.
3. (original) The electronic component assembly of claim 1, wherein the components are selected from a group consisting of an electronic device, a memory device, a logic device and a microprocessor.
4. (original) The electronic component assembly of claim 1, wherein the components have identical or similar functionality in operation.
5. (original) The electronic component assembly of claim 1, wherein the components have a different functionality in operation.

6. (canceled)

7. (original) The electronic component assembly of claim 1, the assembly further comprising at least one external signal communication interface on the flexible printed circuit for communicating signals between the components and external circuits.

8. (canceled) An electronic component assembly, comprising:
a flexible printed circuit;
a first modular section formed on the flexible printed circuit, comprising:
a first component electronically coupled with the flexible printed circuit;
a second component electronically coupled with the flexible printed circuit, the flexible printed circuit folded to position the components in generally mutually facing relation; and,
an inter-component thermal management device disposed between the components, in thermal relation with the components, for removing or stabilizing thermal energy from the components during operation;
a second modular section comprising:
a first component electronically coupled with the flexible printed circuit;
a second component electronically coupled with the flexible printed circuit, the flexible printed circuit folded to position the components in generally mutually facing relation; and,
a further inter-component thermal management device disposed between the components, in thermal relation with the components, for removing or stabilizing thermal energy from the components during operation, the flexible printed circuit being folded to form a stack of the modular sections[.]; and
at least one further thermal management device thermally coupled to at least one of the inter-component thermal management devices.

9. (original) The electronic component assembly of claim 8, wherein the components of the first modular section and the second modular section are disposed on a first side of the flexible printed circuit, and an inter-layer thermal management device is disposed on a second side of the flexible printed circuit opposite to the first side, the flexible printed circuit being folded to form a stack of the modular sections and the inter-layer heat dissipation device.

10. (original) The electronic component assembly of claim 8, wherein the components of the first modular section and the second modular section are disposed on a first side of the flexible printed circuit and a third modular section, similar to the first and second modular sections, is disposed on a second side of the flexible printed circuit opposite to the first side, the flexible printed circuit being folded to form a stack of the modular sections.

11. (canceled)

12. (currently amended) The electronic component assembly of claim [11]8, wherein the ~~second~~ further thermal management device is positioned adjacent to at least one of a front face or a side face of the assembly.

13. (currently amended) An electronic component assembly, comprising:
a flexible printed circuit;
a plurality of modular sections formed on the flexible printed circuit, each modular section comprising:
a first component electronically coupled with the flexible printed circuit;
a second component electronically coupled with the flexible printed circuit, the flexible printed circuit folded to position the components in generally mutually facing relation; and[,]

an inter-component thermal management device disposed between the components, in thermal relation with the components, for removing or stabilizing thermal energy from the components during operation, the flexible printed circuit being folded to form a stack of the modular sections[.]; and

at least one second thermal management device thermally connected to at least one of the inter-component or the inter-layer thermal management devices.

14. (original) The electronic component assembly of claim 13, wherein the modular sections are disposed on a first side of the flexible printed circuit and at least one inter-layer thermal management device is disposed on the second side of the flexible printed circuit opposite to the first layer, the flexible printed circuit being folded to form a stack of the modular sections and the at least one inter-layer thermal management device.

15. (original) The electronic component assembly of claim 14, wherein the modular sections and the inter-layer thermal management devices are positioned to result in an alternate arrangement of the modular sections and the inter-layer thermal management device in the stack.

16. (original) The electronic component assembly of claim 13, wherein the modular sections are disposed on a first side of the flexible printed circuit and a further plurality of modular sections are disposed on the second side of the flexible printed circuit opposite to the first layer, the flexible printed circuit being folded to form a stack of the modular sections.

17. (canceled)

18. (currently amended) The electronic component assembly of claim [17]13, wherein the second thermal management device is positioned adjacent to at least one of a front face or a side face of the assembly.

19. - 36. (canceled)